

Supplementary Information for Chlorine-Mediated Atomic Layer Deposition of HfO₂ on Graphene

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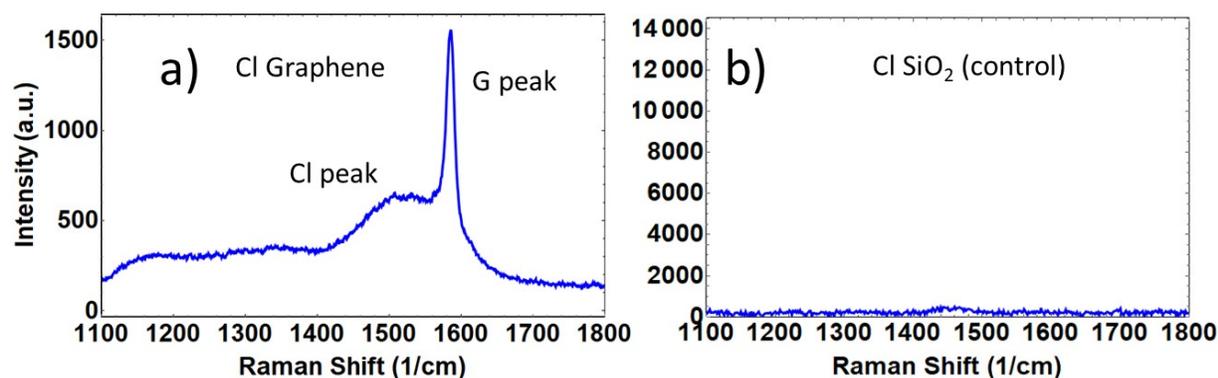


Figure S1: Raman spectra of chlorinated bare SiO₂ (a) and chlorinated graphene (b)

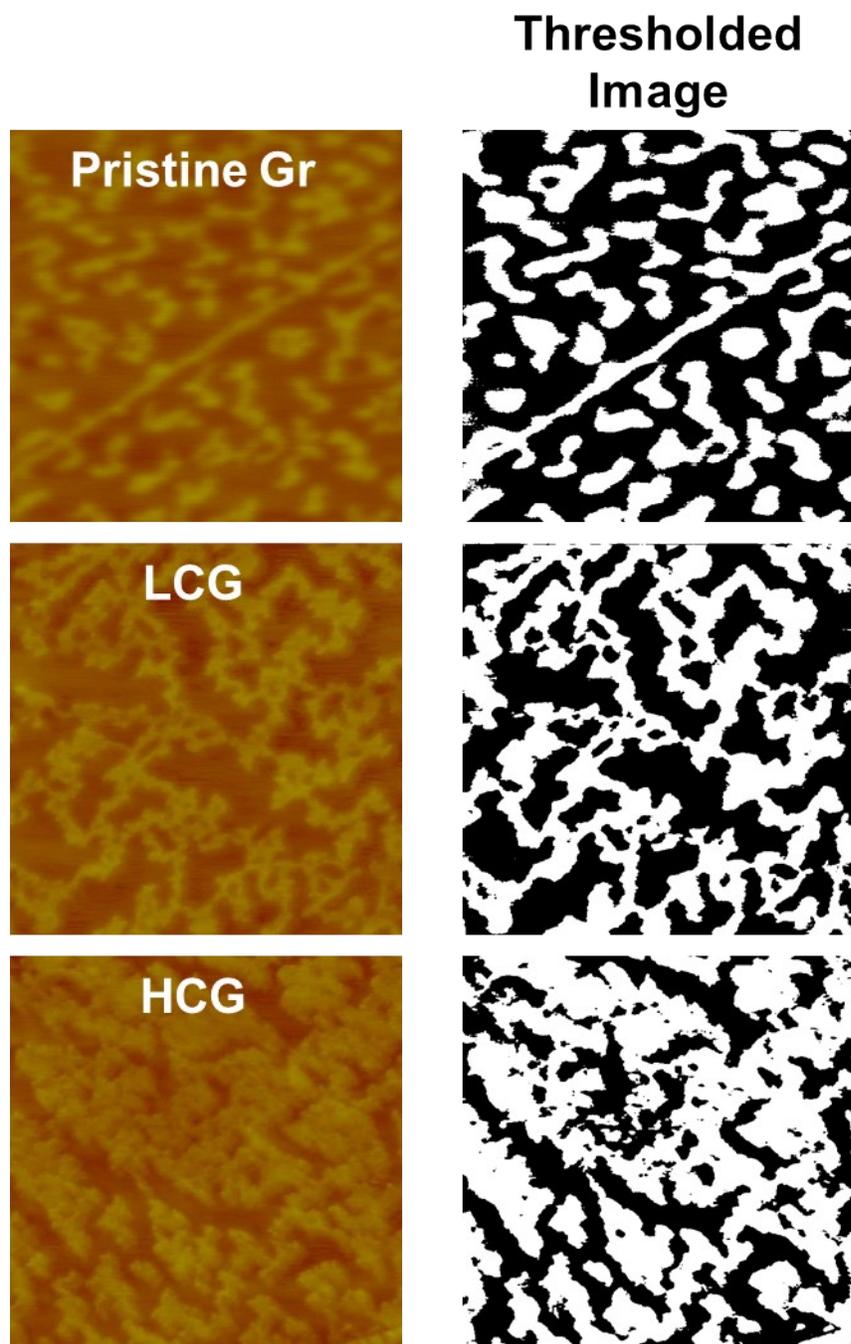


Figure S2: Schematic demonstrating the image thresholding algorithm to calculate coverage of ALD hafnia on graphene

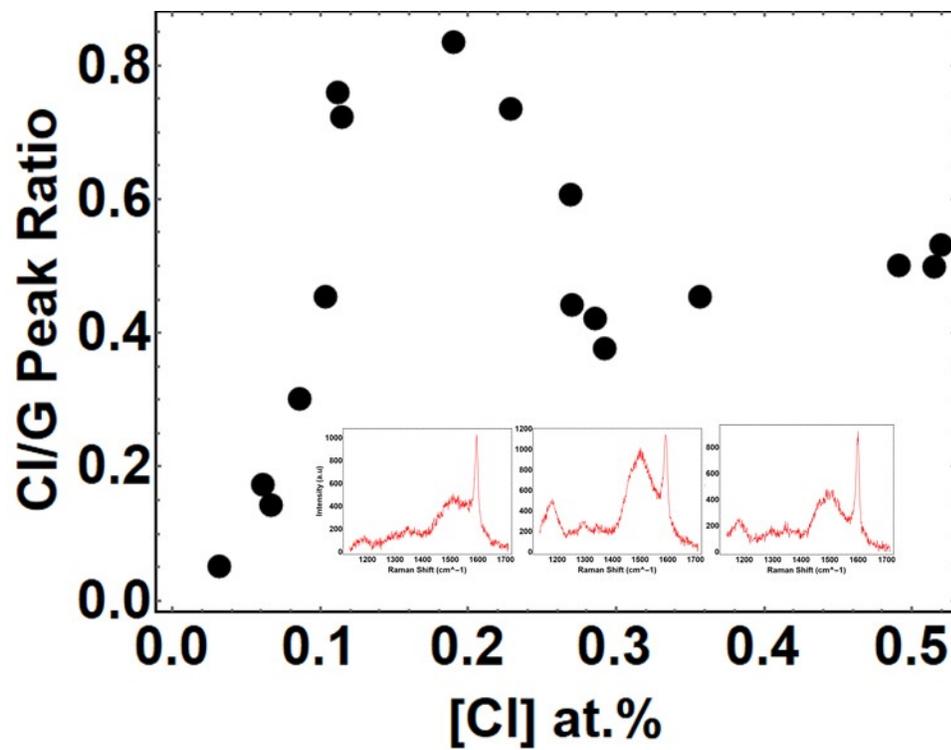


Figure S3: Correlation of the normalized Cl peak intensity (normalized to G peak) and the Cl:C ratio obtained from XPS.

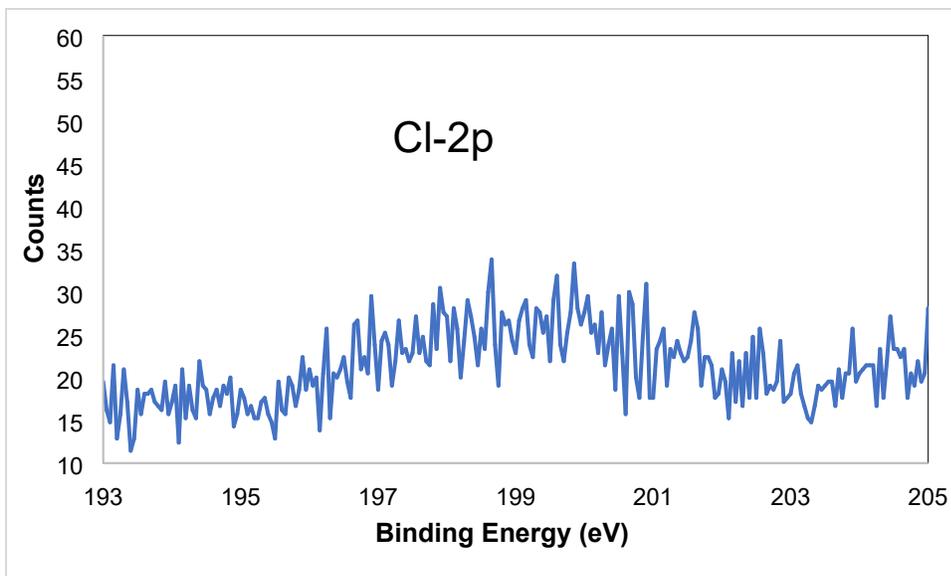


Figure S4: XPS spectrum of Cl-2p region after ALD of 2 nm of Hafnia.

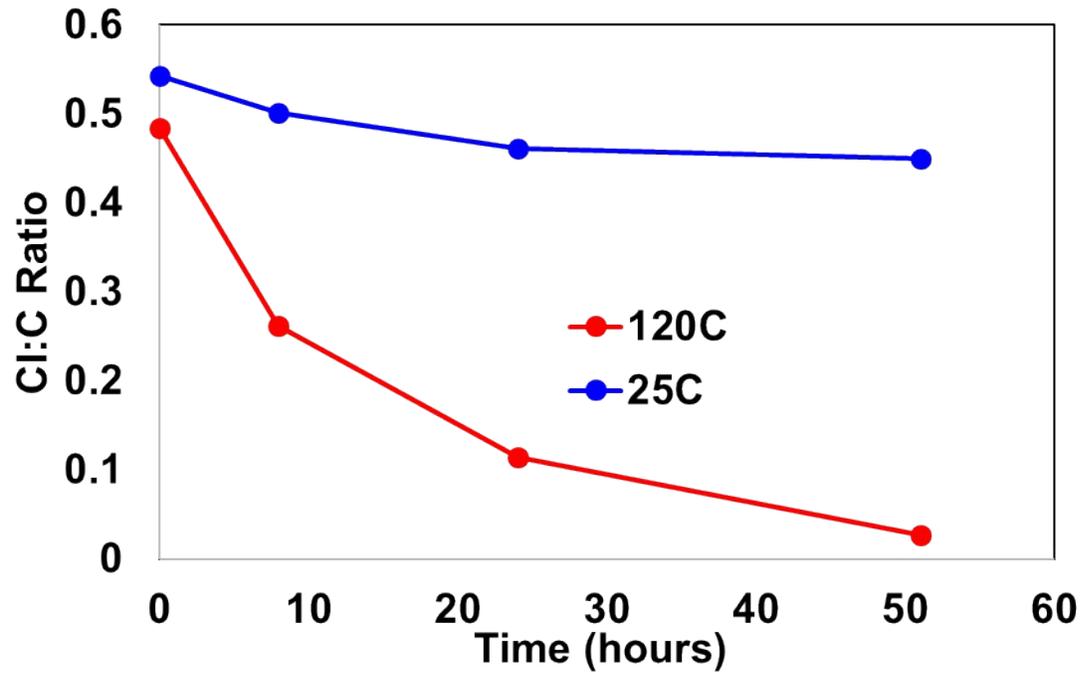


Figure S5: Evolution of Chlorine content over time at different temperatures.

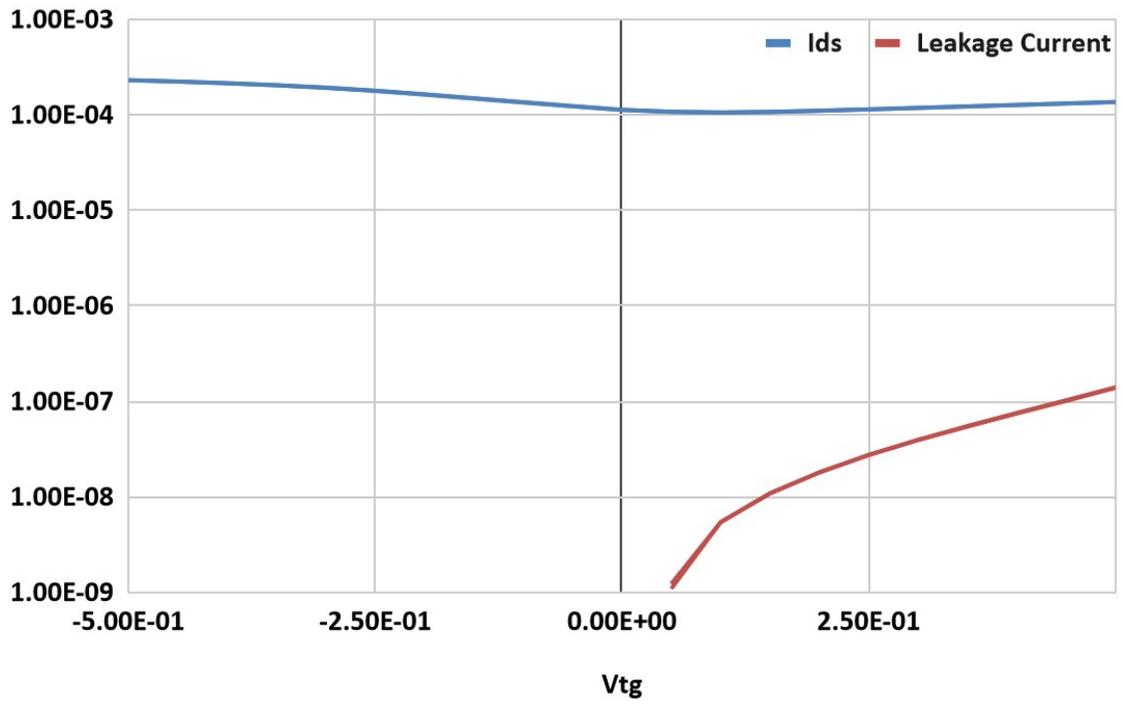


Figure S6: I_{ds} of the top gated device plotted against the leakage current of the device showing that the leakage current is 3 orders of magnitude lower than the I_{ds} .